

### **ABSTRACT**

In a semiconductor laser device 10 including a semiconductor laser element 14, a frame 12 having a front face on which the semiconductor laser element 14 is placed, and a resin molded portion 15 that covers the front and back faces of the frame 12, on a front face side of the frame 12, the semiconductor laser element 14 is enclosed with an enclosure portion 15b of the resin molded portion 15, and the resin molded portion 15 has an open front serving as a laser beam emission window 15a. On a back face side of the frame 12, there is provided an exposed portion 16e enclosed with a U-shaped enclosure portion 15d of the resin molded portion 15, the exposed portion 16e where the frame 12 is exposed to the outside.